

Final Product/Process Change Notification Document #: FPCN22191X2 Issue Date: 25 April 2018

_Title of Change:	Title of Change: Update to SOIC-8 Insourcing to ON Semiconductor Philippines (OSPI) Factory from HANA (Thailand) – Phase 1		
Proposed first ship da	te: 23 June 2018	23 June 2018	
Contact information:	Contact your local ON Semiconductor	Contact your local ON Semiconductor Sales Office or <scott.brow@onsemi.com></scott.brow@onsemi.com>	
Samples:	Contact your local ON Semiconductor	Contact your local ON Semiconductor Sales Office or <pcn.samples@onsemi.com></pcn.samples@onsemi.com>	
Additional Reliability (Data: Contact your local ON Semiconductor	Contact your local ON Semiconductor Sales Office or <kyungwon.kang@onsemi.com></kyungwon.kang@onsemi.com>	
Type of notification:	to implementation of the change. ON Semiconductor will consider this of	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <pcn.support@onsemi.com>.</pcn.support@onsemi.com>	
Change Part Identifica	trace code marking on Line 2 is of the 2-digit date code. Product marked wi label of the box and reel, the ASSY LO label on Page 2 at the following URL	Product marked with date code 1810 or later may be built from current factory or from OSPI Factory. The trace code marking on Line 2 is of the form ALYW where A = Assembly Location, L = Wafer Lot ID and YW is a 2-digit date code. Product marked with "P" as the assembly location will be from OSPI. Additionally on the label of the box and reel, the ASSY LOC: PO will also indicate product assembled in OSPI. Please see sample label on Page 2 at the following URL http://www.onsemi.com/pub/Collateral/LABELRM-D.PDF to see the location of the ASSY LOC.	
Change category:	☐ Wafer Fab Change ☐ Assemb	bly Change	
Change Sub-Category(Manufacturing Site Manufacturing Production	Change/Addition Material Change	□ Datasheet/Product Doc change □ Shipping/Packaging/Marking □ Other:	
Sites Affected:	ON Semiconductor Sites: ON Carmona, Philippines	External Foundry/Subcon Sites: HANA, Thailand	
Description and Purpose:			
This update notification is to correct (2) typos from FPCN22191X issued March 8, 2018. Page 2 identified the change in marking for all products affected by this change. The following products were listed incorrectly. The Line 1 marking for the products listed in this Update Notification are as listed:			
	OPN	Line 1 Marking	
	FAN7380MX_OP	7380	
	FAN7842MX	7842	
Reliability Data Summary:			
See original FPCN22191X			
Electrical Characteristic Summary:			
Electrical characteristics are not impacted by this change. Electrical comparison reports are available upon request			
List of Affected Standard Parts:			
	Part Number	Qualification Vehicle	
	FAN7380MX_OP		
	FAN7842MX	FAN7380MX	

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